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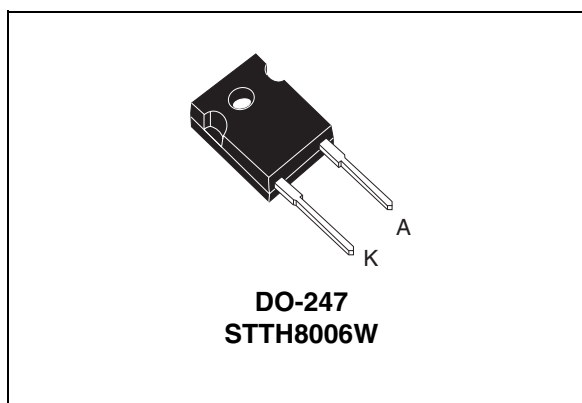


STTH8006

Turbo 2 ultrafast high voltage rectifier

Main product characteristics

$I_{F(AV)}$	80 A
V_{RRM}	600 V
T_j	175 °C
V_F (typ)	1.02 V
t_{rr} (max)	70 ns



Features and benefits

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses

Description

The STTH8006, which is using ST Turbo 2 600V technology, is specially suited for use in switching power supplies, and industrial applications, as rectification and discontinuous mode PFC boost diode. Thanks to its low V_F characteristics, this device exhibits high performances in free-wheeling applications.

Order Code

Part number	Marking
STTH8006W	STTH8006W

Table 1. Absolute ratings (limiting values, at $T_{amb} = 25\text{ °C}$, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	RMS forward current		113	A
$I_{F(AV)}$	Average forward current	$T_c = 75\text{ °C}$ $\delta = 0.5$	80	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}$	500	A
T_{stg}	Storage temperature range		-65 to + 175	°C
T_j	Maximum operating junction temperature		175	°C

Characteristics

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1 Characteristics

Table 2. Thermal resistance

Symbol	Parameter	Value (max).	Unit
$R_{th(j-c)}$	Junction to case	0.75	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$		50	μA
		$T_j = 150\text{ °C}$		160	1600	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 80\text{ A}$		1.60	V
		$T_j = 150\text{ °C}$		1.02	1.30	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$
2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:
 $P = 0.98 \times I_{F(AV)} + 0.004 I_{F(RMS)}^2$

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit	
t_{rr}	Reverse recovery time	$T_j = 25\text{ °C}$	$I_F = 0.5\text{ A}$ $I_{rr} = 0.25\text{ A}$ $I_R = 1\text{ A}$			70	ns
			$I_F = 1\text{ A}$ $di_F/dt = 50\text{ A}/\mu\text{s}$ $V_R = 30\text{ V}$		75	105	
I_{RM}	Reverse recovery current	$T_j = 125\text{ °C}$	$I_F = 80\text{ A}$ $V_R = 400\text{ V}$ $di_F/dt = 100\text{ A}/\mu\text{s}$		14	19	A
t_{fr}	Forward recovery time	$T_j = 25\text{ °C}$	$I_F = 80\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$			600	ns
V_{FP}	Forward recovery voltage	$T_j = 25\text{ °C}$	$I_F = 80\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$		3.7		V

Figure 1. Conduction losses versus average forward current

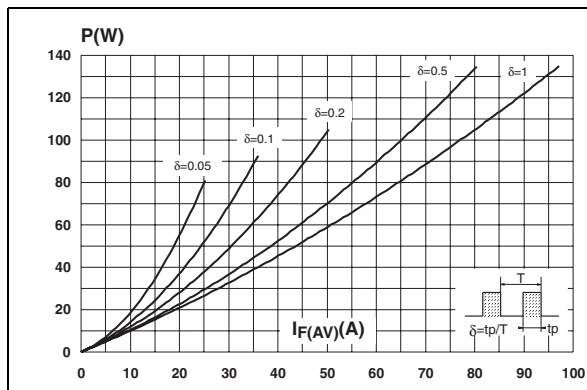
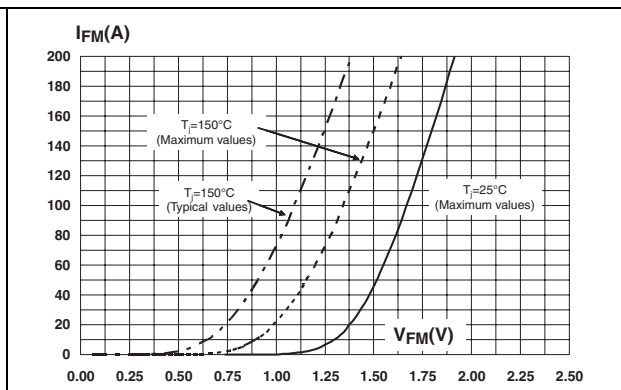


Figure 2. Forward voltage drop versus forward current



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Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

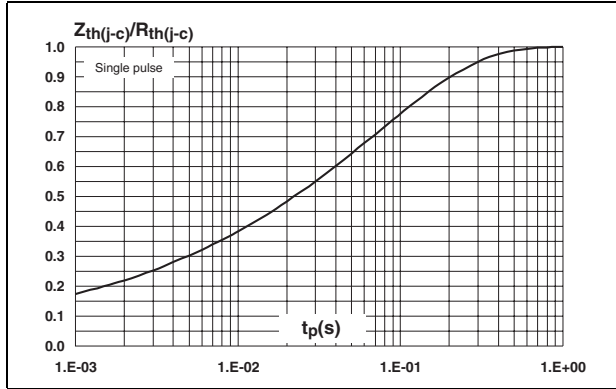


Figure 4. Peak reverse recovery current versus di_F/dt (typical values)

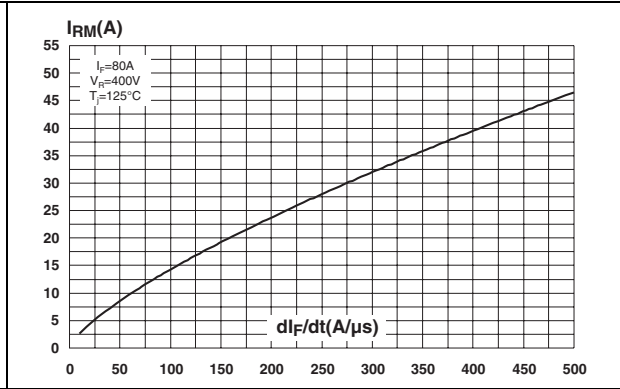


Figure 5. Reverse recovery time versus di_F/dt (typical values)

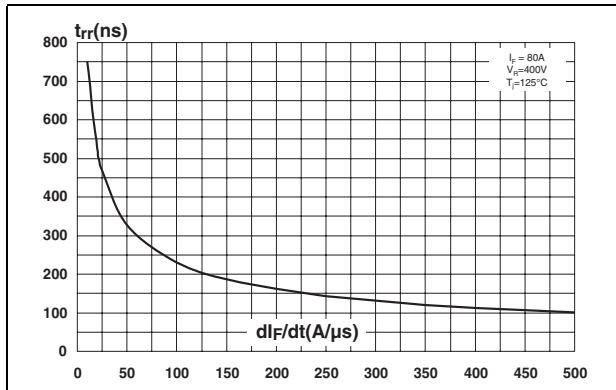


Figure 6. Reverse recovery charges versus di_F/dt (typical values)

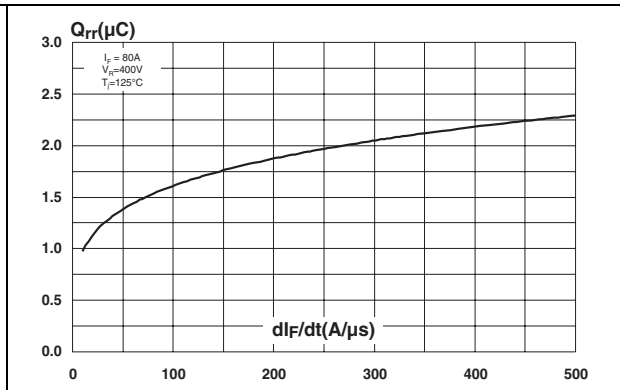


Figure 7. Relative variations of dynamic parameters versus junction temperature

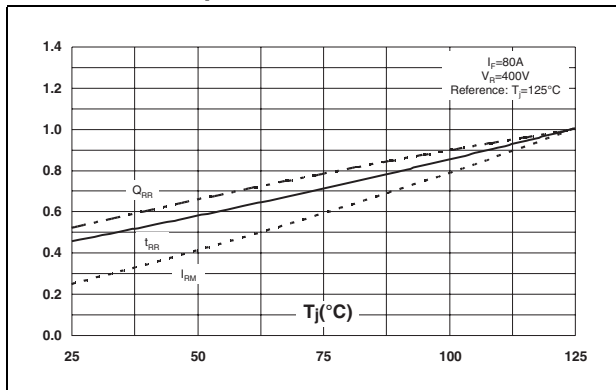
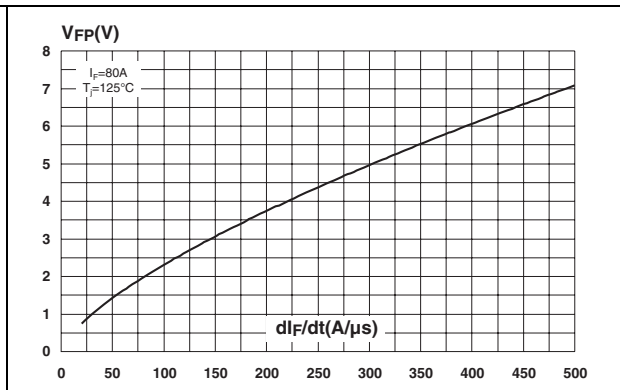


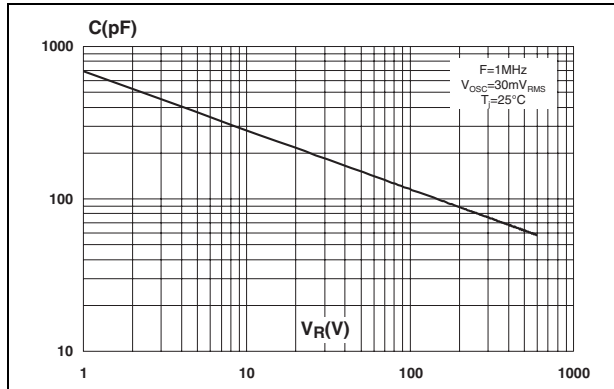
Figure 8. Transient peak forward voltage versus di_F/dt (typical values)



Package information

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Figure 9. Junction capacitance versus reverse voltage applied (typical values)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 Nm.
- Maximum torque value: 1.0 Nm.

Table 5. DO-247 dimensions

REF	DIMENSIONS					
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

STTH8006**Ordering information**

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

3 Ordering information

Part number	Marking	Package	Weight	Base qty	Delivery mode
STTH8006W	STTH8006W	DO-247	4.40 g	30	Tube

4 Revision history

Date	Revision	Changes
15-Dec-2006	1	Initial release.

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